



PRODUCT CHANGE NOTIFICATION

PCN No.: 2172017-1

Issue Date: 2/17/2017

IXYS Colorado has found it necessary to change certain products. This notification is to inform you that this change may affect your products. If you have any comments on this notice please contact IXYS Colorado within 30 days of the PCN.

REASONS FOR CHANGE:

In order to increase production volume and to reduce product lead times, IXYSRF is introducing higher capacity molds for device packages: DE150, DE275, DE375, DE475 for all MOSFET and Gate Driver part numbers.

PCN TIME LINE:

Devices to be phased in starting February 2017

| IXYSRF Part No.: | Product Type: | Package Type: | Recommended Actions: |
|-------------------|---------------------|---------------|----------------------|
| DE475 all devices | MOSFET | DE475 | None |
| DE375 all devices | MOSFET | DE375 | None |
| DE275 all devices | MOSFET/Gate drivers | DE275 | None |
| DE150 all devices | MOSFET | DE150 | None |
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PCN CREATED/UPDATED

DATE: 2/17/2017

ORIGINATOR: Gilbert Bates Product Engineer

REVIEWED BY: Steve Krausse General Manager

The following random device and part number is used to identify characteristics of the mold changes.

Physical Appearance: These pictures outline the change in package features.

Old mold

No embossments

Country Of Origin printed on package



New mold

Embossments now include:

Upper left- IXYS logo

Upper right- Number representing mold slot position, 1 of 16 positions

Lower middle- Country Of Origin, and has replaced the printing of the COO

